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PATENT

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COMMISSIONER FOR PATENTS
Washington, D.C. 20231
Box PATENT APPLICATION

Sir:
Transmitted herewith for filing is the patent application of:

Inventor(s): Dr. Bernd Borchert, DE

For: Halbleiterlaserchip und Verfahren zum Herstellen eines Halbleiterlaserchips

This application includes:

16 pages: specification, claims, abstract and reference number list
3 sheets of drawings, formal/ X Informal
 photographs


Also enclosed is:

- An Assignment of the invention to Assignee(s):
 Infineon Technologies North America Corp.
- A certified copy of Application
- Declaration and Power of Attorney
- Information Disclosure Statement pursuant to 37 CFR 1.56
 - Form PTO-1449
 - Form PTO-1595
- X Post Card

The filing fee has been calculated as shown below:

FOR:	(Col. 1) NO. FILED	(Col. 2) NO. EXTRA RATE	OTHER THAN A SMALL ENTITY FEE
BASIC FEE	XXXXXXXX	XXXXXXXX	XXXXX \$710
TOTAL CLAIMS	<u>10</u> - 20 =	<u> </u>	X \$18 = \$ <u> </u>
INDEP CLAIMS	<u>2</u> - 3 =	<u> </u>	X \$80 = \$ <u> </u>
* MULTIPLE DEPENDENT CLAIM PRESENTED			+ 270 = \$000
ASSIGNMENT(S)	<u> </u>		X \$40 = \$ <u> </u>
TOTAL			<u>\$710</u>

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